

# 74HC4049

## Hex inverting HIGH-to-LOW level shifter

Rev. 3 — 30 December 2010

Product data sheet

### 1. General description

The 74HC4049 is a high-speed Si-gate CMOS device and is pin compatible with the 4049 of the 4000B series. It is specified in compliance with JEDEC standard no. 7A.

The 74HC4049 provides six inverting buffers with a modified input protection structure, which has no diode connected to  $V_{CC}$ . Input voltages of up to 15 V may therefore be used.

This feature enables the inverting buffers to be used as logic level translators, which will convert high level logic to low level logic, while operating from a low voltage power supply. For example 15 V logic (4000B series) can be converted down to 2 V logic.

The actual input switch level remains related to  $V_{CC}$  as mentioned in the static characteristics. At the same time each part can be used as a simple inverter without level translation.

### 2. Features and benefits

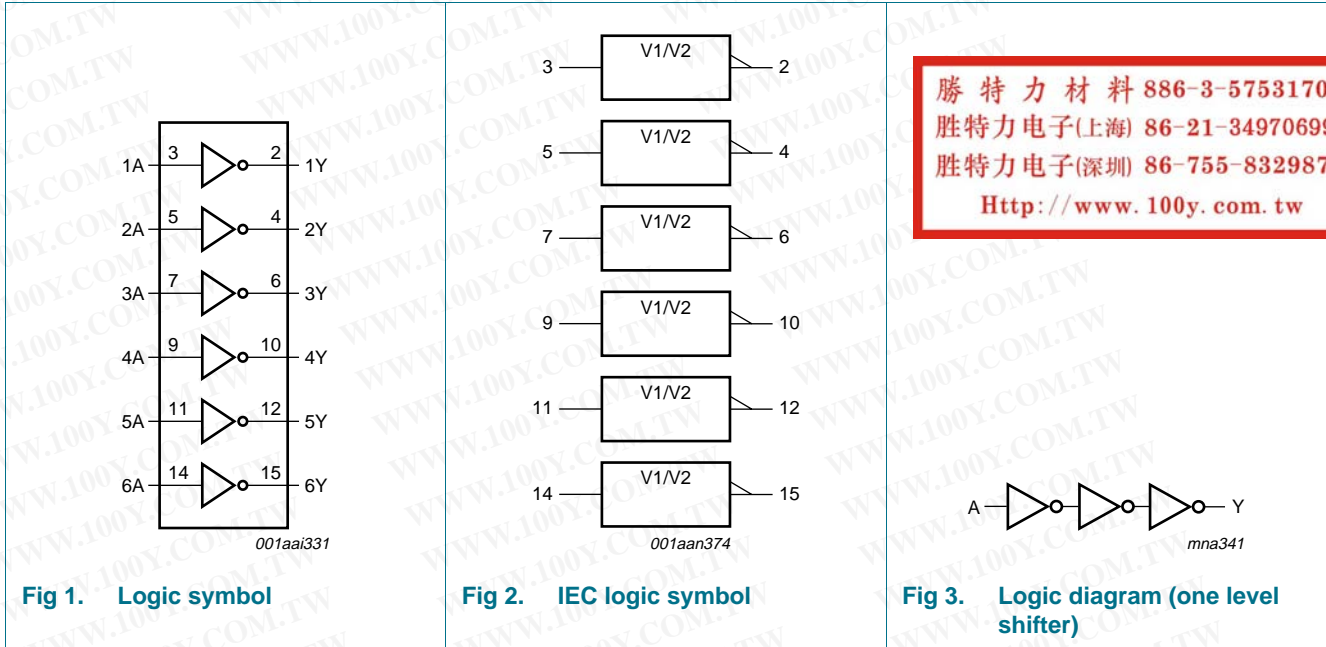
- Low-power dissipation
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2 000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Ordering information

Table 1. Ordering information

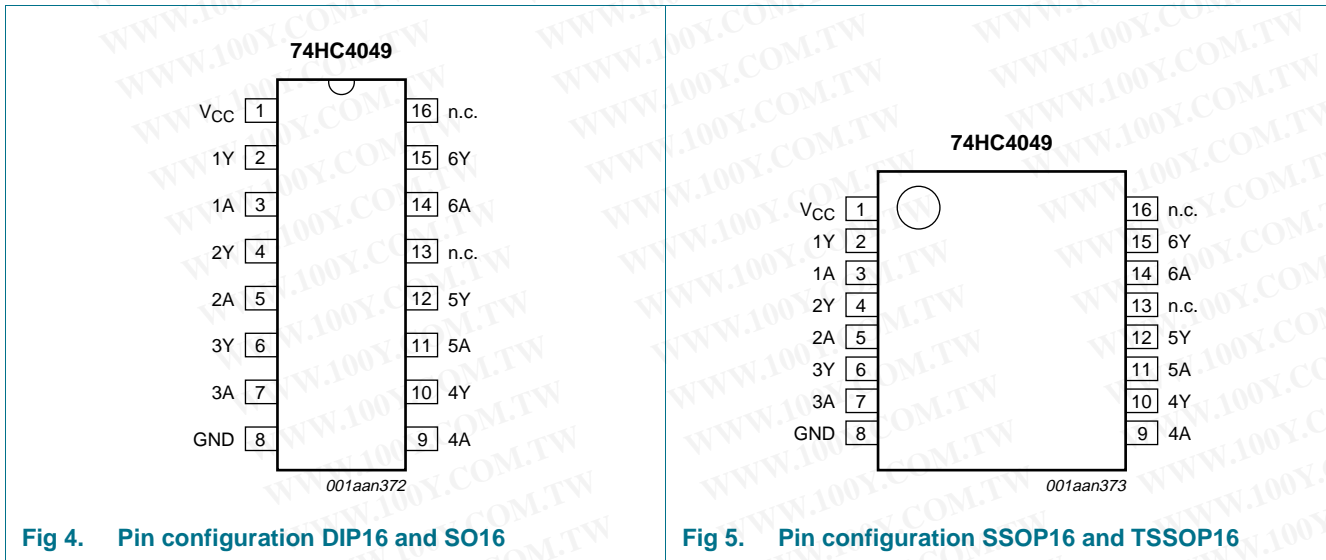
Type number	Package			
	Temperature range	Name	Description	Version
74HC4049N	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HC4049D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HC4049DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HC4049PW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1

4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

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Table 2. Pin description

Symbol	Pin	Description
V <sub>CC</sub>	1	supply voltage
1Y to 6Y	2, 4, 6, 10, 12, 15	output
1A to 6A	3, 5, 7, 9, 11, 14	input
GND	8	ground (0 V)
n.c.	13, 16	not connected

6. Functional description

Table 3. Function table [\[1\]](#)

Input	Output
nA	nY
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7	V
V <sub>IK</sub>	input clamping voltage		-0.5	+16	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V	-20	-	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V	-	±20	mA
I <sub>O</sub>	output current	V <sub>O</sub> = -0.5 V to (V <sub>CC</sub> + 0.5 V)	-	±25	mA
I <sub>CC</sub>	supply current		-	+50	mA
I <sub>GND</sub>	ground current		-	-50	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	DIP16 package	<a href="#">[1]</a>	750	mW
		SO16, SSOP16 and TSSOP16 packages	<a href="#">[2]</a>	500	mW

[1] For DIP20 package: P<sub>tot</sub> derates linearly with 12 mW/K above 70 °C.

[2] For SO16: P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.

For SSOP16 and TSSOP16 packages: P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.

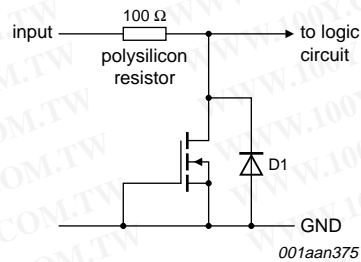


Fig 6. Input protection for the 74HC4049

## 8. Recommended operating conditions

Table 5. Recommended operating conditions  
 Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		2.0	5.0	6.0	V
$V_I$	input voltage		0	-	15	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}; V_I = 2.0\text{ V}$	-	-	625	ns/V
		$V_{CC} = 4.5\text{ V}; V_I = 4.5\text{ V}$	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}; V_I = 6.0\text{ V}$	-	-	83	ns/V
		$V_{CC} = 6.0\text{ V}; V_I = 10.0\text{ V}$	-	-	81	ns/V
		$V_{CC} = 6.0\text{ V}; V_I = 15.0\text{ V}$	-	-	83	ns/V

## 9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ °C}$			$T_{amb} = -40\text{ °C to } +85\text{ °C}$		$T_{amb} = -40\text{ °C to } +125\text{ °C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	1.3	-	1.5	-	1.5	-	V
		$V_{CC} = 4.5\text{ V}$	3.15	2.4	-	3.15	-	3.15	-	V
		$V_{CC} = 6.0\text{ V}$	4.2	3.1	-	4.2	-	4.2	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	0.7	0.5	-	0.5	-	0.5	V
		$V_{CC} = 4.5\text{ V}$	-	1.8	1.35	-	1.35	-	1.35	V
		$V_{CC} = 6.0\text{ V}$	-	2.3	1.8	-	1.8	-	1.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 2.0\text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 4.5\text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 6.0\text{ V}$	5.9	6.0	-	5.9	-	5.9	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.98	-	-	3.84	-	3.7	-	V
	$I_O = -5.2\text{ mA}; V_{CC} = 6.0\text{ V}$	5.48	-	-	5.34	-	5.2	-	V	

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	-	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	-	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	-	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	-	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	-	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
		V <sub>I</sub> = 15 V; V <sub>CC</sub> = 6.0 V	-	-	±0.5	-	±5.0	-	±5.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = 15 V or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	2.0	-	20	-	40	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); C<sub>L</sub> = 50 pF unless otherwise specified; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t <sub>pd</sub>	propagation delay	nA to nY; see <a href="#">Figure 7</a> [1]								
		V <sub>CC</sub> = 2.0 V	-	28	85	-	105	-	130	ns
		V <sub>CC</sub> = 4.5 V	-	10	17	-	21	-	26	ns
		V <sub>CC</sub> = 5 V; C <sub>L</sub> = 15 pF	-	8	-	-	-	-	-	ns
		V <sub>CC</sub> = 6.0 V	-	8	14	-	18	-	22	ns
t <sub>t</sub>	transition time	Yn; see <a href="#">Figure 7</a> [2]								
		V <sub>CC</sub> = 2.0 V	-	19	75	-	95	-	110	ns
		V <sub>CC</sub> = 4.5 V	-	7	15	-	19	-	22	ns
		V <sub>CC</sub> = 6.0 V	-	6	13	-	16	-	19	ns
C <sub>PD</sub>	power dissipation capacitance	C <sub>L</sub> = 50 pF; f = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> [3]	-	14	-	-	-	-	-	pF

[1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

[2] t<sub>t</sub> is the same as t<sub>THL</sub> and t<sub>TLH</sub>.

[3] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

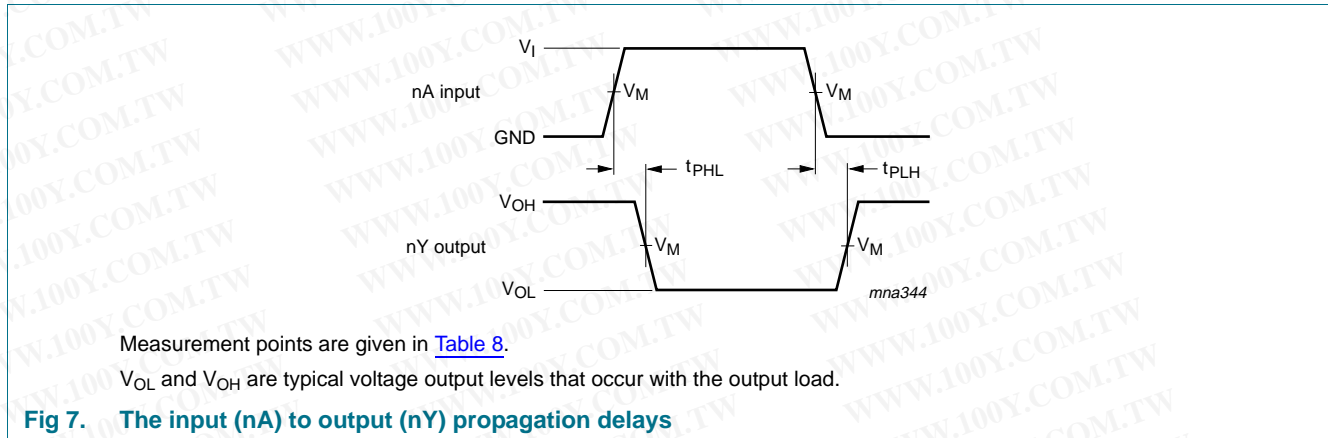
f<sub>o</sub> = output frequency in MHz;

C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

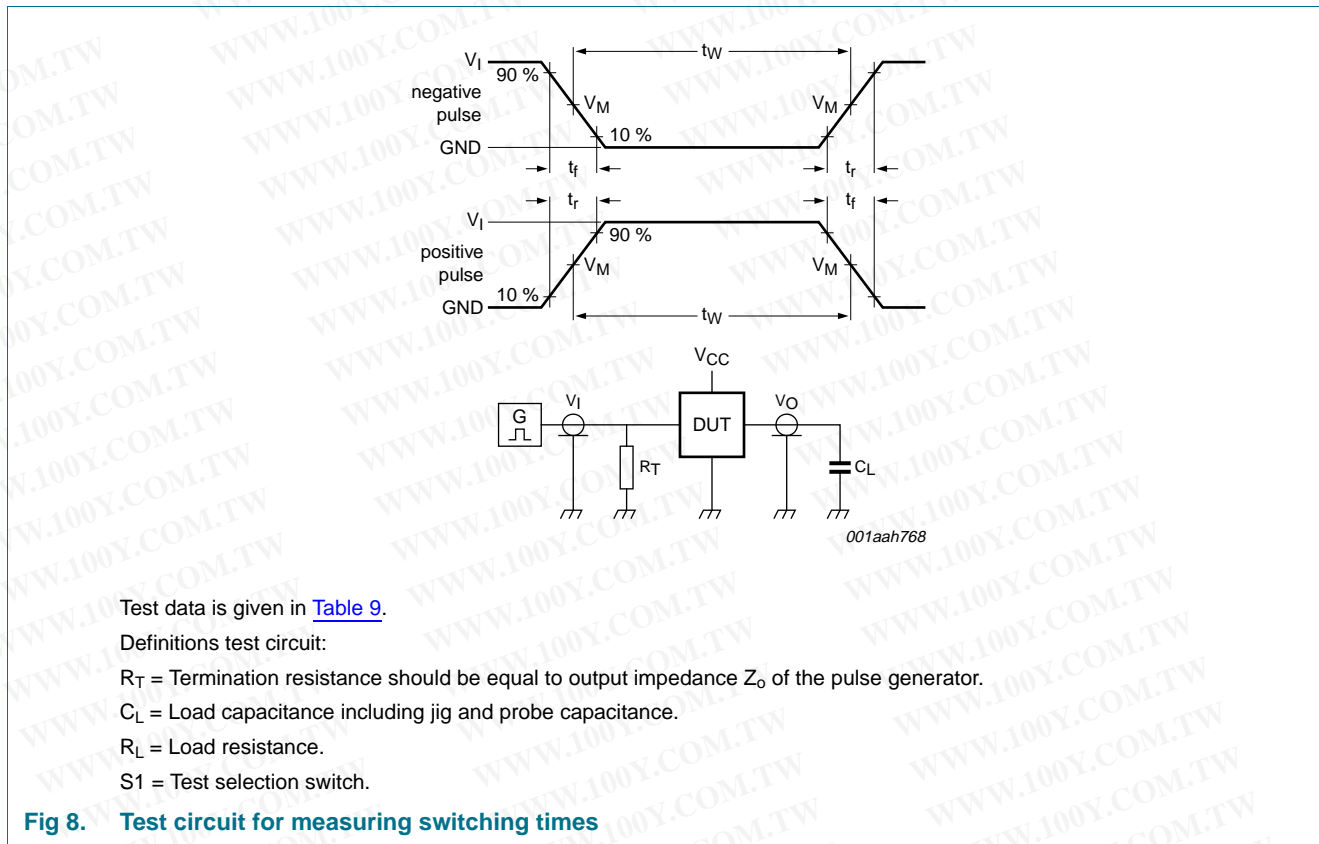
N = number of inputs switching;  
 $\Sigma(C_L \times V_{CC}^2 \times f_o) =$  sum of outputs.

## 11. Waveforms



**Table 8. Measurement points**

Type	Input	Output
	74HC4049	$V_M$ 0.5V <sub>CC</sub>



**Table 9. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
74HC4049	$V_{CC}$	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

12. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

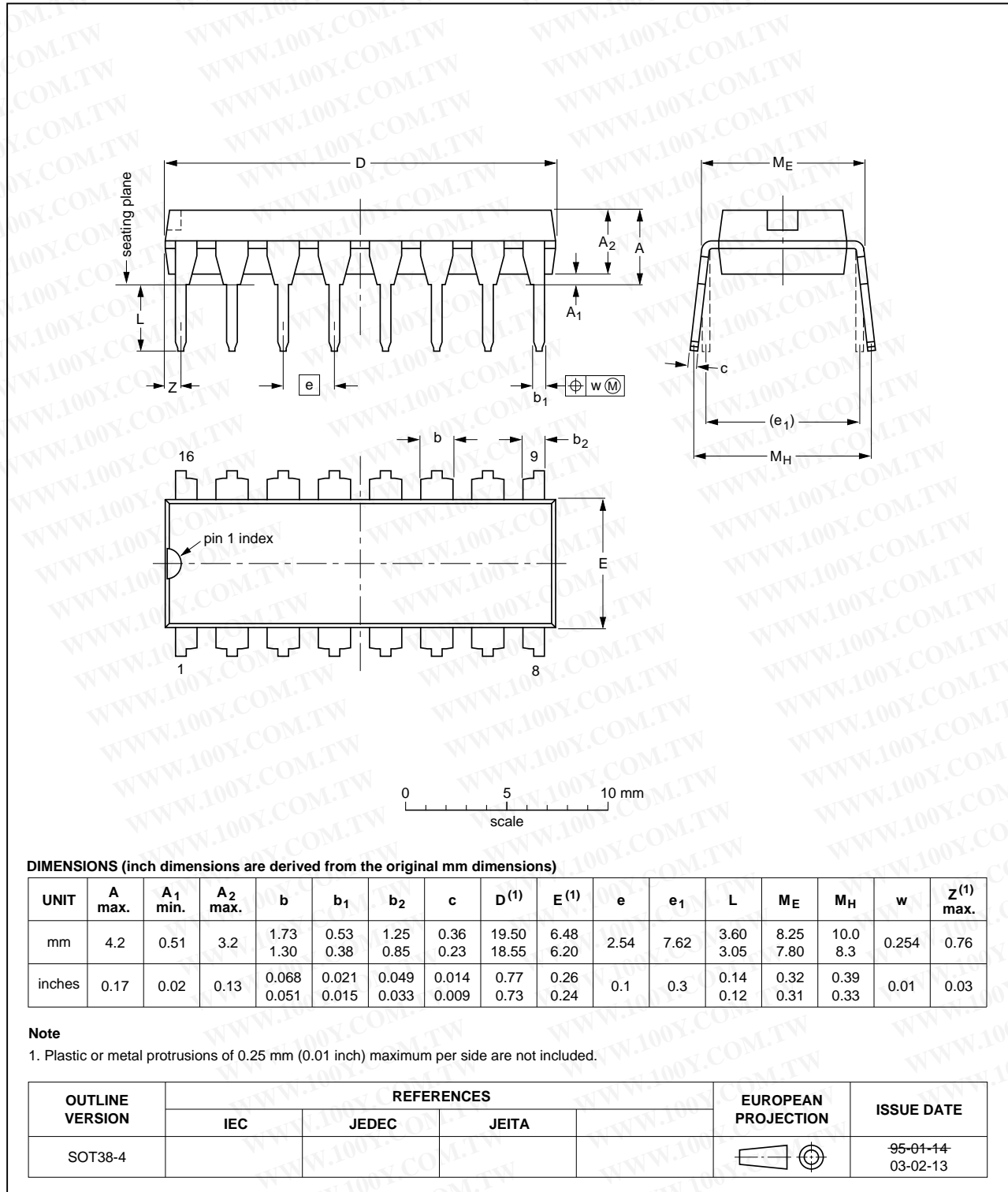


Fig 9. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

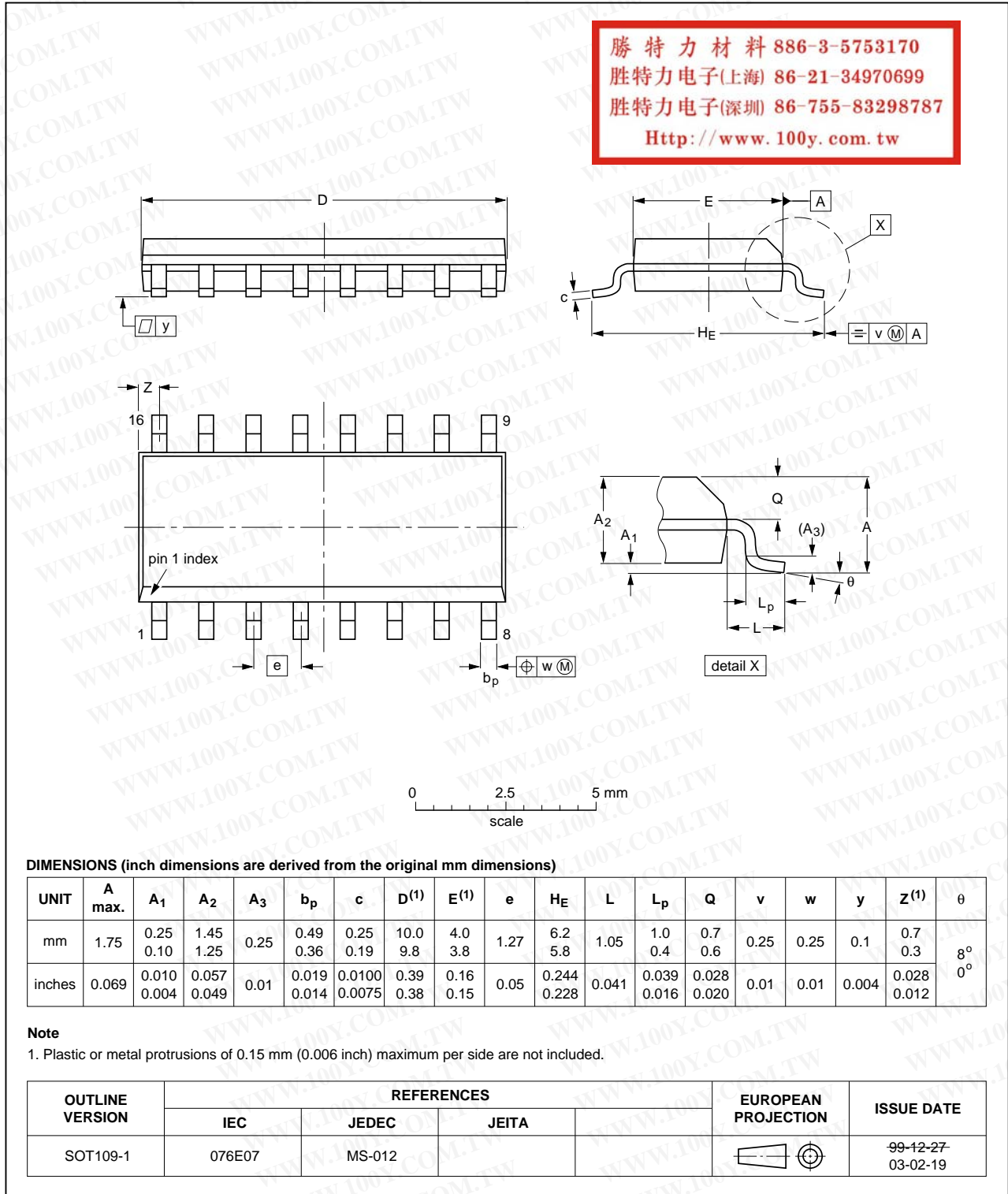


Fig 10. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

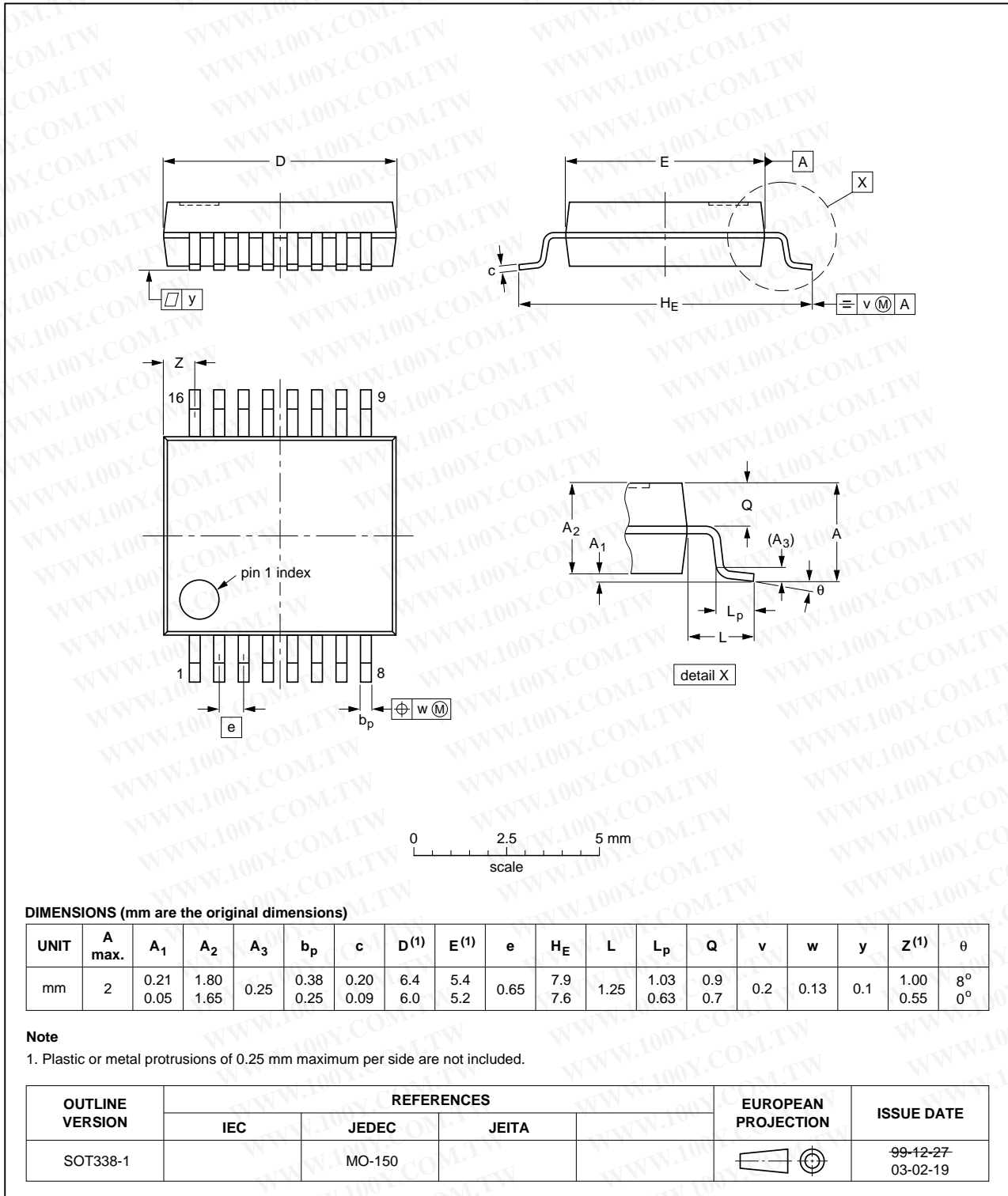


Fig 11. Package outline SOT338-1 (SSOP16)

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TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

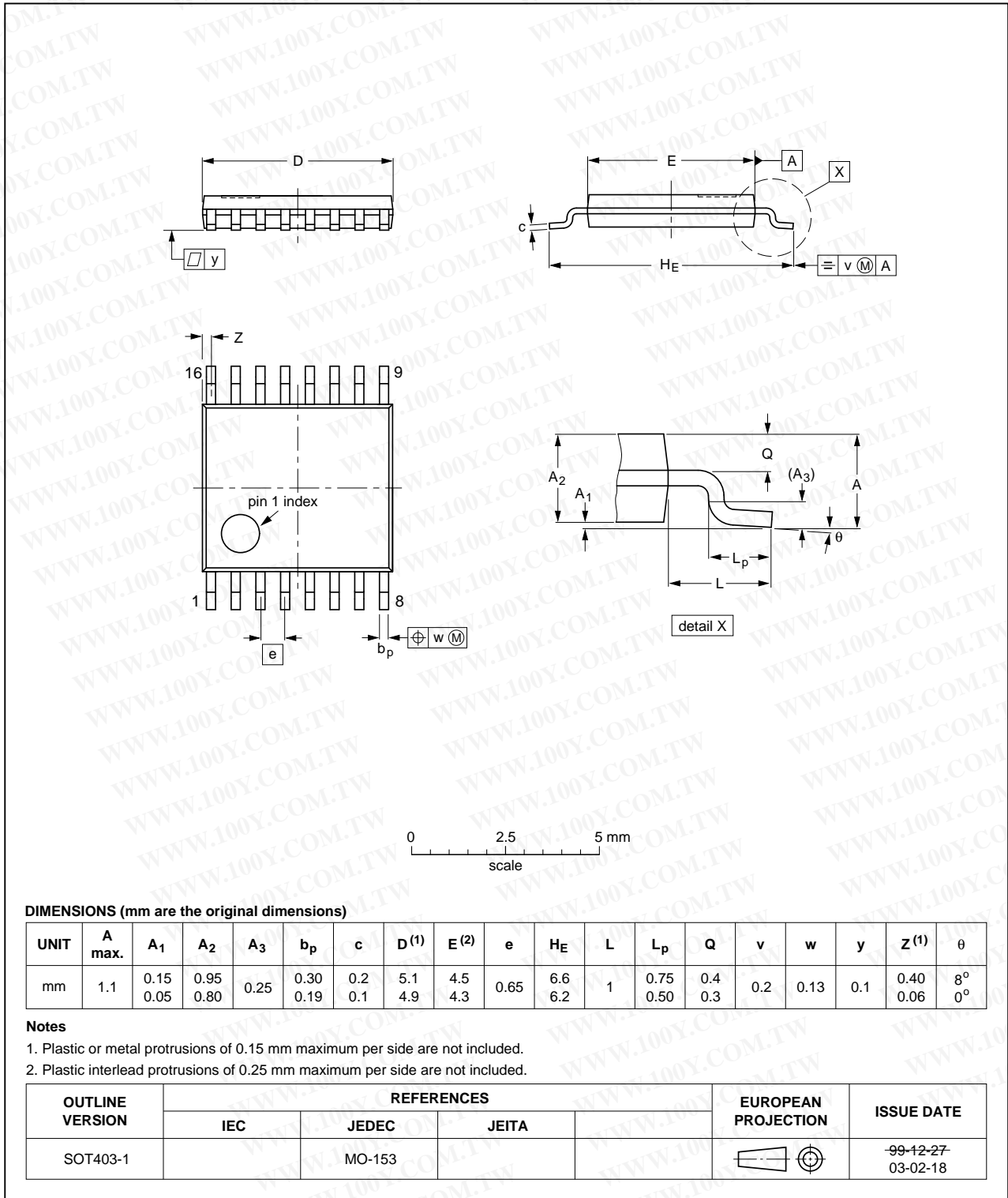


Fig 12. Package outline SOT403-1 (TSSOP16)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

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## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC4049 v.3	20101230	Product data sheet	-	74HC4049_CNV v.2
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li>Added type number 74HC4049PW (TSSOP16 package).</li> </ul>			
74HC4049_CNV v.2	19970827	Product specification	-	-

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### 15.1 Data sheet status

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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